

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/809,182 Confirmation No. 6820
Applicant(s) : UMENO, Kuniharu et al.
Filed : 03/25/2004
TC/A.U. : 1712
Examiner : Robert E. Sellers
Title : Resin Composition for Encapsulating Semiconductor Chip and
Semiconductor Device Therewith

Docket No. : 033036.076
Customer No. : 25461

MAIL STOP RCE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Sir:

AMENDMENT ACCOMPANYING RCE

Please amend the above-identified application as follows:

Amendments to the specification are reflected beginning on page 2.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks/Arguments begin on page 9 of this paper.

Attachments:

Corrected Declaration – 4 pgs.
Certified Translations of JP 2003-083937 and 2003-083938
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